



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No. : 10/507,213  
Confirmation : 5089  
Applicant : Dietmar BIRGEL  
Filed : September 15, 2004  
Title : Method for populating and soldering a circuit board,  
reflow oven and circuit board for such a method  
TC/A.U. : 1793  
Examiner : M. Aboagye  
Docket No. : BIRG3004/FJD  
Customer No. : 23364

**RESPONSE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**Introductory Comments**

The following amendments and corresponding remarks are being submitted herewith pursuant to the provisions of 37 CFR 1.114 in response to the Office Action of May 3, 2009 in this RCE application.